

3403J-VB Datasheet

P-Channel 30-V (D-S) MOSFET

| PRODU | CT SUMMARY | | | |
|---------------------|-----------------------------------|---------------------------------|-----------------------|--|
| V _{DS} (V) | $R_{DS(on)}\left(\Omega\right)$ | I _D (A) ^d | Q _g (Typ.) | |
| - 30 | 0.056at V _{GS} = - 10 V | - 20 | 19 nC | |
| - 30 | 0.072 at V _{GS} = -4.5 V | - 15 | 19110 | |

FEATURES

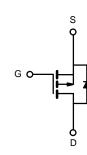
- Halogen-free
- Trench Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested



RoHS

APPLICATIONS

- Load Switch
- · Notebook Adaptor Switch



P-Channel MOSFET

| TO-251 | |
|----------|---------------------------------|
| | <u>_</u> |
| 0 | |
| | Drain Connected to Drain-Tab |
| G D | S |
| Top View | / |

| Parameter | Symbol | Limit | Unit | |
|--|-----------------------------------|------------------|-----------------------|----|
| Drain-Source Voltage | V_{DS} | - 30 | | |
| Gate-Source Voltage | V_{GS} | ± 20 | - V | |
| | T _C = 25 °C | | - 20 | |
| Continuous Prois Current /T = 150 °C) | T _C = 70 °C | 1 , [| - 15 | |
| Continuous Drain Current (T _J = 150 °C) | T _A = 25 °C | - I _D | -7.9 ^{a, b} | |
| | T _A = 70 °C | 1 | - 5.6 ^{a, b} | _ |
| Pulsed Drain Current | <u>.</u> | I _{DM} | - 60 | A |
| Continuous Courses Brain Binds Coursest | T _C = 25 °C | | - 20 | |
| Continuous Source-Drain Diode Current | T _A = 25 °C | - I _S | - 7.9 ^{a, b} | |
| Avalanche Current | . 0.4 | I _{AS} | - 20 | |
| Single-Pulse Avalanche Energy L = 0.1 mH | | E _{AS} | 20 | mJ |
| | T _C = 25 °C | | 20 | |
| Maniana Pana Pissinatian | T _C = 70 °C | | 15 | W |
| Maximum Power Dissipation | T _A = 25 °C | - P _D | 2.7 ^{a, b} | VV |
| | T _A = 70 °C | | 1.7 ^{a, b} | |
| Operating Junction and Storage Temperature Range | T _J , T _{stg} | - 55 to 150 | °C | |

| THERMAL RESISTANCE RATINGS | | | | | | |
|---|--------------|------------|---------|---------|------|--|
| Parameter | | Symbol | Typical | Maximum | Unit | |
| Maximum Junction-to-Ambient ^{a, c} | t ≤ 10 s | R_{thJA} | 38 | 46 | °C/W | |
| Maximum Junction-to-Foot | Steady State | R_{thJF} | 20 | 25 | C/VV | |

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W.
- d. Based on T_C = 25 °C.



| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit | |
|---|--|---|-------|----------------|------------|------|--|
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$ | - 30 | | | V | |
| V _{DS} Temperature Coefficient | $\Delta V_{DS}/T_{J}$ | J 250A | | - 34 | | mV/ | |
| V _{GS(th)} Temperature Coefficient | $\Delta V_{GS(th)}/T_{J}$ | I _D = - 250 μA | | 5.3 | | °C | |
| Gate-Source Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_{D} = -250 \mu A$ | - 1.4 | | - 2.5 | V | |
| Gate-Source Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$ | | | ± 100 | nA | |
| Zero Gate Voltage Drain Current | I _{DSS} | $V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$ | | | - 1 - 5 | μA | |
| On-State Drain Current ^a | I _{D(on)} | V _{DS} ≥ - 10 V, V _{GS} = - 10 V | - 20 | | | Α | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | V _{GS} = - 10 V, I _D = - 6 A V _{GS} = - 4.5 V, I _D = - 4 A | | 0.056 0.072 | | Ω | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = - 10 V, I _D = - 6 A | | 28 | | S | |
| Dynamic ^b | 0.0 | 20 1 2 | | | | L | |
| Input Capacitance | C _{iss} | | | 1150 | | | |
| Output Capacitance | C _{oss} | $V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | | 205 | | pF | |
| Reverse Transfer Capacitance | C _{rss} | | | 140 | | | |
| Total Gate Charge | Q _g | $V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -6 \text{ A}$ | | 27 | 43 | nC | |
| - | | <u></u> | | 19 | 25 | | |
| Gate-Source Charge | Q_{gs} | $V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -6 \text{ A}$ | | 6 | | | |
| Gate-Drain Charge | Q_{gd} | | | 12 | | | |
| Gate Resistance | R_{g} | f = 1 MHz | 0.5 | 2.2 | 4.4 | Ω | |
| Turn-On Delay Time | t _{d(on)} | | | 13 | 25 | _ | |
| Rise Time | t _r | $V_{DD} = -15 \text{ V}, R_{L} = 1.5 \Omega$ | | 12 | 24 | | |
| Turn-Off DelayTime | t _{d(off)} | $I_D \cong$ - 10 A, V_{GEN} = - 10 V, R_g = 1 Ω | | 40 | 70 | | |
| Fall Time | t _f | | | 9 | 18 | ns | |
| Turn-On Delay Time | t _{d(on)} | | | 48 | 80 | | |
| Rise Time | t_{r} $V_{DD} = -15 \text{ V}, R_{L} = 1.5 \Omega$ | | | 92 | 160 | 1 | |
| Turn-Off DelayTime | t _{d(off)} | $I_D \cong -6$ A, $V_{GEN} = -4.5$ V, $R_g = 1$ Ω | | 34 | 60 |] | |
| l Time t _f | | | 19 | 35 | | | |
| Drain-Source Body Diode Characteris | stics | | | | | | |
| Continous Source-Drain Diode Current | I _S | T _C = 25 °C | | | - 4.1 | Α | |
| Pulse Diode Forward Current | I _{SM} | | | | - 60 | | |
| Body Diode Voltage | V_{SD} | $I_{S} = -3 \text{ A}, V_{GS} = 0 \text{ V}$ | | - 0.75 | - 1.2 | V | |
| Body Diode Reverse Recovery Time | t _{rr} | | | 27 | 45 | ns | |
| Body Diode Reverse Recovery Charge | Q _{rr} | I _F = -6 A, dl/dt = 100 A/μs, T _{.I} = 25 °C | | 16 | 27 | nC | |
| Reverse Recovery Fall Time | t _a | i _F - · σ Λ, αι/αι = 100 Λ/μs, 1 _J = 25 C | | 12 | | ns | |
| Reverse Recovery Rise Time | t _b | | | 15 | | | |

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

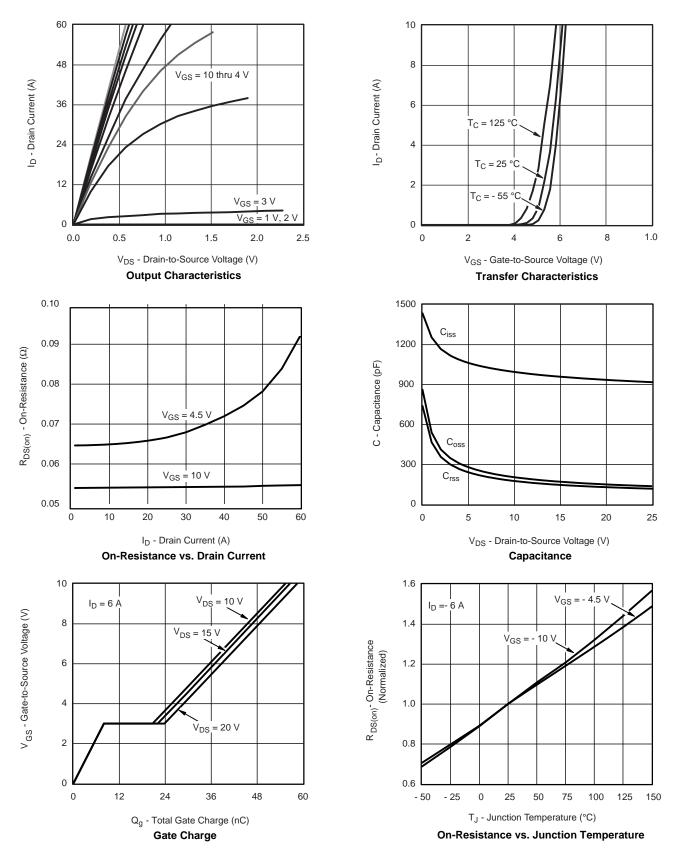
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a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

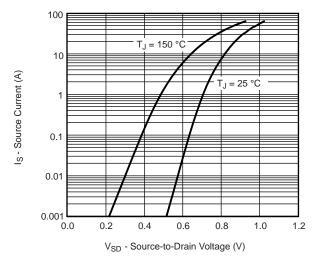


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

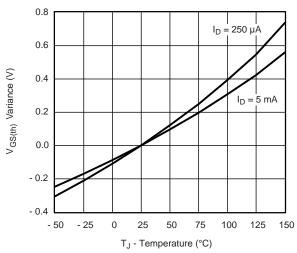




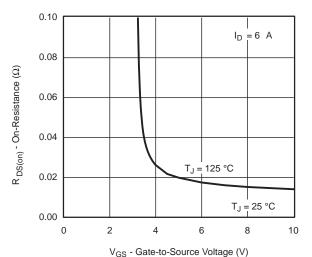
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Source-Drain Diode Forward Voltage



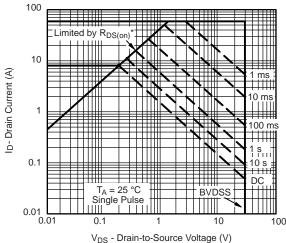
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

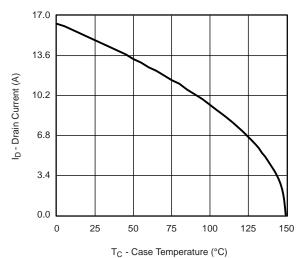


* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

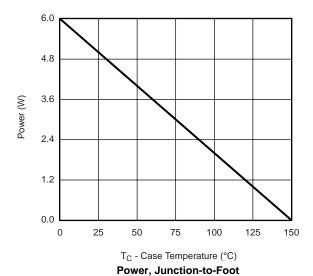
Safe Operating Area

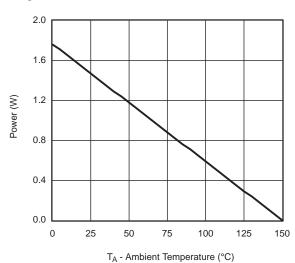


MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*





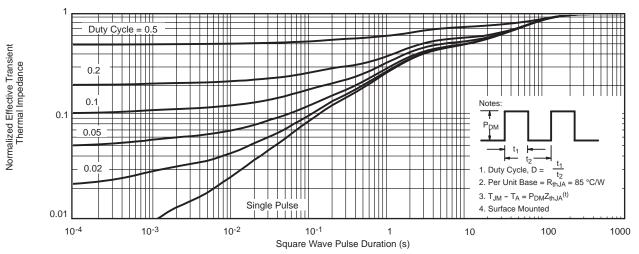
Power Derating, Junction-to-Ambient

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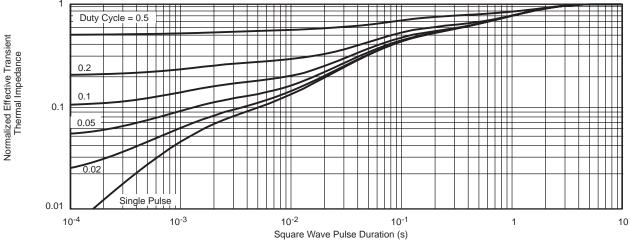
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



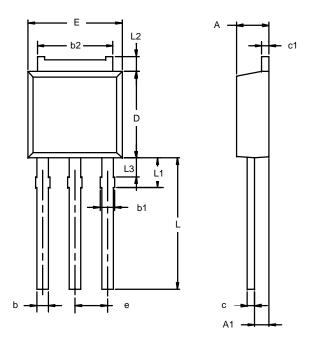
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



TO-251AA



Note: Dimension L3 is for reference only.

| | MILLIM | IETERS | INC | HES | |
|------------|----------|--------|-----------|-------|--|
| Dim | Min | Max | Min | Max | |
| Α | 2.21 | 2.38 | 0.087 | 0.094 | |
| A 1 | 0.89 | 1.14 | 0.035 | 0.045 | |
| b | 0.71 | 0.89 | 0.028 | 0.035 | |
| b1 | 0.76 | 1.14 | 0.030 | 0.045 | |
| b2 | 5.23 | 5.43 | 0.206 | 0.214 | |
| С | 0.46 | 0.58 | 0.018 | 0.023 | |
| с1 | 0.46 | 0.58 | 0.018 | 0.023 | |
| D | 5.97 | 6.22 | 0.235 | 0.245 | |
| Е | 6.48 | 6.73 | 0.255 | 0.265 | |
| е | 2.28 BSC | | 0.090 BSC | | |
| L | 3.89 | 9.53 | 0.153 | 0.375 | |
| L1 | 1.91 | 2.28 | 0.075 | 0.090 | |
| L2 | 0.89 | 1.27 | 0.035 | 0.050 | |
| L3 | 1.15 | 1.52 | 0.045 | 0.060 | |

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